The ISA–200 is designed for in– ert gas ion beam etching as well as for reactive ion beam etching. He–backside cooling, work piece heating, SIMS for end point detec– tion, CAIBE, interface for clean room, beam monitoring with Faraday cup array and other helpful features are available. A second ion source can be attached to combine the etching process with an ion beam assisted coating process via up to four sput– ter targets.



## **TECHNICAL DATA**

#### **WORK PIECE DATA**

Diameter:	Ø200 mm (Ø8'')
Thickness:	50 mm (2'')
Weight:	max. 2 kg (4.4 lbs)
Contact angle:	0 – 180°
Rotation speed:	0 – 10 rpm
Shape:	plane, spherical, aspherical, freeform

< 2min.

#### SINGLE LOAD LOCK SYSTEM

Loading time:

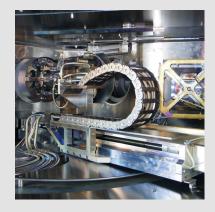
#### **AXIS SYSTEM**

Type: 200 Travel:

### X, A, B X = 300 mm $A = 0 - 120^{\circ}$ B = 360°

#### DIMENSIONS

Weight:	2200 kg (4840 lbs)
WxHxD:	2.55 m x 2.48 m x 2.25 m
	(100'' x 97'' x 89'')
Footprint:	3.5 m x 3 m
	(138'' x 118'')



NTG

# ISA**200**